

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

03.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	123		2
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3
		70	L2	
C-RaS-FR4-ML-0.406mm-070+070-TG150-HF...	50203124	406		4
		70	L3	
				A01
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	183		5
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6
		70	L4	
C-RaS-FR4-ML-0.406mm-070+070-TG150-HF...	50203124	406		7
		70	L5	
				A02
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	183		8
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		9
		70	L6	
C-RaS-FR4-ML-0.406mm-070+070-TG150-HF...	50203124	406		10
		70	L7	
				A03
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	123		11
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		12
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	13

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

2320 µm

Version 1.2.20.35

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